

ABSTRACT

An apparatus in which a device electrode pad in an electronic device and a connecting conductor pattern in a substrate are connected to each other through a plurality of wire thin lines which differ from one another in mechanical characteristic frequencies. Even if the frequency of vibration applied to the apparatus from the exterior coincides with the characteristic frequency of the given wire thin line so that the wire thin line is broken, it does not coincide with the characteristic frequency of the other wire thin line. Accordingly, no resonance phenomenon occurs in the other wire thin line, thereby reducing a probability that the wire thin line is broken.